

## 118-06 (SP)

### ELECTRICALLY CONDUCTIVE, EPOXY DIE ATTACH ADHESIVE

#### DESCRIPTION

118-06(SP) is a screen-printable, B-Stageable, electrically conductive, one part epoxy coating and adhesive. 118-06(SP) can also be applied by dipping and syringe dispensing. This system features excellent thermal stability, outstanding chemical resistance and excellent high temperature properties. Applications include, but are not limited to assembling electrical and electronic components.

#### UNIQUE FEATURES

- \* Excellent Electrical Conductivity
- \* Outstanding Printability
- \* B-Stageable
- \* Long Screen Life
- \* Excellent Chemical Resistance
- \* Excellent High Temperature Performance
- \* Low Ionics

#### IONIC CONTENT

|  |        |  |
|--|--------|--|
| Chloride   | <10ppm |  |
| Sodium   | <10ppm |  |
| Potassium  | <10ppm |  |
| (Typical properties are not intended to be used as specification limits) |        |  |

#### TYPICAL UNCURED PROPERTIES

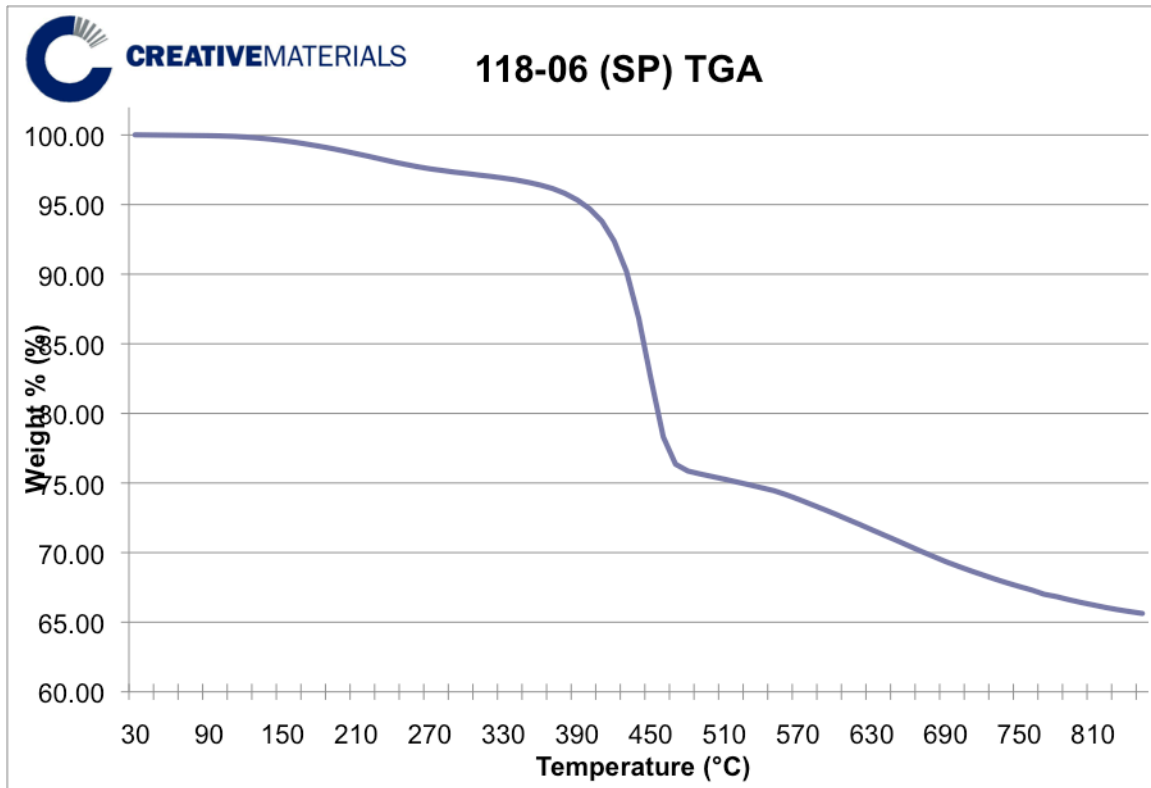
| Property  | Value  | Units                 |
|---|--------|-----------------------|
| Viscosity – Brookfield HAT Viscometer<br>@ 10 rpm @ 25° C | 23,000 | cps                   |
| Specific Gravity  | 2.68   | water = 1             |
| Filler  | Silver | N/A                   |
| Percent Silver (cured)                                    | >74    | %                     |
| Theoretical Coverage @ 0.001" Wet Thickness <sup>1</sup>  | 22     | in <sup>2</sup> /gram |
| Screen Life   | 8      | hrs                   |
| Solids  | 86     | %                     |
| Color   | Silver | N/A                   |

<sup>1</sup> Dependent on screen mesh and material

#### TYPICAL CURED PROPERTIES

| Property   | Value       | Units  |
|--|-------------|--------|
| Operating Temperature                              | -55 to +230 | °C     |
| Peak Temperature                                   | 325         | °C     |
| Volume Resistivity                                 | 0.0002      | Ω - cm |
| Glass transition Temperature – Tg                  | 100         | °C     |
| Coefficient of Thermal Expansion                   | 50          | ppm/°C |
| T-Shear Strength                                   | 2100        | Psi    |
| Weight Loss @ 300° C, TGA                          | 2.77        | %      |
| Differential Scanning Calorimetry (DSC)<br>Peak Tc | 168         | °C     |
| Δ Hc   | -33.4       | J/g    |

**TYPICAL CURED PROPERTIES – cont.**



**CURING GUIDELINES**

| Temperature (°C) | Time (min.) |  |
|------------------|-------------|--|
| 150              | 60          | These temperatures and times are presented as a guide only. The end-user is encouraged to experiment to determine optimum curing schedule. |
| 175              | 30          |  |
| 200              | 15          |  |

**HANDLING AND STORAGE**

118-06(SP) is a one component epoxy system and is ready to use as received. Product should be stored frozen to maintain consistent flow properties. **Allow 118-06(SP) to warm up to room temperature before opening container.** Prior to using, mix thoroughly to re-suspend fillers. If needed, 118-06(SP) can be thinned with small amounts of Creative Materials' 113-12 thinner.

**SHELF LIFE**

| Storage Temperature | Containers | B-Staged Film |
|---------------------|------------|---------------|
| 25°C                | 2 months   | 1 month       |
| -10°C               | 6 months   | 3 months      |

**B-STAGE PROCEDURE**

Apply adhesive to substrate. Apply heat to advance curing to the non-tacky stage (when cooled to room temperature). A temperature of 125° C for 2 – 3 minutes is required (B-stage time is mass related). The user is encouraged to experiment for optimum drying time at a given temperature. Store on release liner to prevent contamination.

**BONDING PROCEDURE**

*All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.*

To use, carefully align parts to be bonded, apply uniform pressure to maintain location. Follow curing guidelines given above. Timing should start once adhesive and substrate reach curing temperature.

1. As with all adhesive bonds, surface preparation is a vital part of the process. Carefully clean both surfaces to be bonded with MEK if possible. If MEK is not compatible with the surfaces to be bonded, another suitable solvent may be used.
2. Allow cleaned surfaces to dry completely.
3. Die cut 118-06(SP) to the of the size of interface area, remove one of the protective liners, position onto one of the surfaces to be bonded, and warm the substrate/adhesive to 50°C-70°C.
4. By applying slight pressure, laminate the film/adhesive to the substrate smoothing out any trapped air. Allow to cool to room temperature and peel off the other release liner.
5. Position the other substrate and apply a clamp to provide constant pressure.
6. Cure for 1 hour at 150°C.
7. Remove pressure. Part is ready for use.

#### **HEALTH AND SAFETY**

Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

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**REVISION DATE: 5/22/07 REVISION: E**